

IN THE CLAIMS:

Please cancel claim 17 without prejudice or disclaimer, and amend claim 5. This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-4 (canceled).

Claim 5 (Currently Amended): A multilayer printed wiring board comprising:

- a substrate;
- a plated through-hole formed in the substrate;
- a solvent-free insulative filling material filled in the plated through-hole;
- a conductor layer plated on an exposed surface of the solvent-free insulative filling material;
- an insulating layer formed on a surface of the conductor layer;
- a conductive pattern layer formed on a surface of the insulating layer; and
- a via conductor connecting the conductor layer and the conducting pattern layer;

wherein the solvent-free insulative filling material includes a filler, a thermosetting epoxy resin, a curing catalyst and a dicyandiamide curing agent,

wherein the filling material has cured with a uniform composition without localizing at least the filler, the thermosetting epoxy resin and the dicyandiamide curing agent,

wherein the plated through-hole has a diameter ~~[[of]]~~ between 50 μm and 200 μm
~~or smaller,~~

wherein the dicyandiamide curing agent is used to reduce deterioration in
adhesive strength between the solvent-free insulative filling material and the conductor
layer, and

wherein the curing catalyst comprises a urea compound; and

wherein the filler is substantially spherical particles having an average particle
size of 0.1 to 12 μm and a maximum particle size of 75 μm or smaller.

Claim 6 (Previously Presented): The multilayer printed wiring board according to claim
5, wherein the conductor layer, the insulating layer and conductor pattern layer are
provided in this order.

Claims 7-10 (Canceled).

Claim 11 (Previously Presented): The multilayer printed wiring board according to claim
10, wherein the urea compound is a material selected from the group consisting of
dimethylurea compound, aromatic urea compound, alicyclic urea compound and
halogenated urea compound.

Claim 12 (Previously Presented): The multilayer printed wiring board according to claim 10, wherein the urea compound is a material selected from the group consisting of dimethylurea compound, aromatic urea compound and alicyclic urea compound.

Claim 13 (Previously Presented): The multilayer printed wiring board according to claim 5, wherein the dicyandiamide curing agent has at least one form selected from the group consisting of powders, dendrites, and flakes.

Claim 14 (Previously Presented): The multilayer printed wiring board according to claim 13, wherein the dicyandiamide curing agent is powder having an average particle size of 0.1 to 100 μm .

Claim 15 (Previously Presented): The multilayer printed wiring board according to claim 13, wherein the dicyandiamide curing agent is powder having an average particle size of 1 to 30 μm .

Claim 16 (Previously Presented): The multilayer printed wiring board according to claim 13, wherein the dicyandiamide curing agent is powder having an average particle size of 1 to 15 μm .

Claim 17 (Canceled).